HFZT

ABS2 ---ABS10

SILICON BRIDGE RECTIFIER

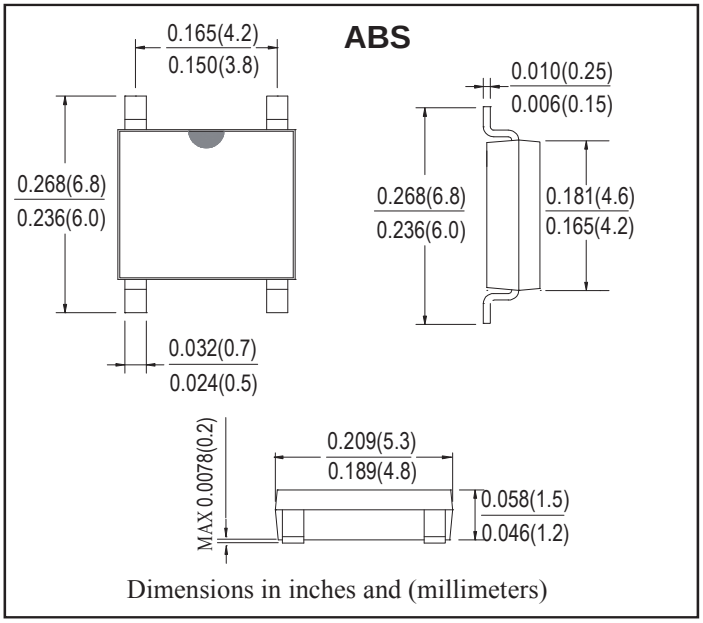
REVERSE VOLTAGE : 200 --- 1000 V CURRENT: 0.8 A

FEATURES

- ●Glass passivated die construction
- ●Low forward voltage drop
- ●High current capability
- ●High surge current capability
- ●Designed for surface mount application
- ●Plastic material-UL flammability 94V-0

MECHANICAL DATA

- ●Case: ABS molded plastic
- ●Terminals: plated leads solderable per MIL-STD-202, Method 208
- ●Polarity: as marked on case
- ●Mounting position: Any
- ●Marking: type number



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25℃ ambient temperature unless otherwise specified.
Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{DC}	200	400	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T_A=30℃ (Note 2)@T_A=30℃	I_O	0.5 0.8					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
Forward Voltage per element @IF=0.4A	V_{FM}	0.95					V
Peak Reverse Current @T_A =25℃ At Rated DC Blocking Voltage @T_A =125 ℃	I_R	5.0 500					uA
Typical Thermal Resistance per leg (Note 3)	$R_{\theta JA}$ $R_{\theta JL}$	62.5 25					℃/W
Operating and Storage Temperature Range	T_J,T_{STG}	-55to+150					℃

Note:1. Mounted on glass epoxy PC board with 1.3mm^2 solder pad.
2. Mounted on aluminum substrate PC board with 1.3mm^2 solder pad.
3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

RATINGS AND CHARACTERISTIC CURVES

FIG.1 MAXIMUM FORWARD CURRENT DERATING CURVE

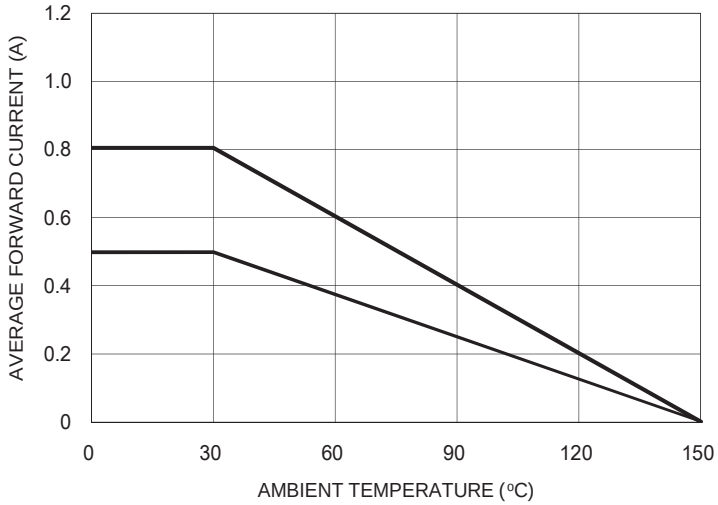


FIG. 2 TYPICAL FORWARD CHARACTERISTIC

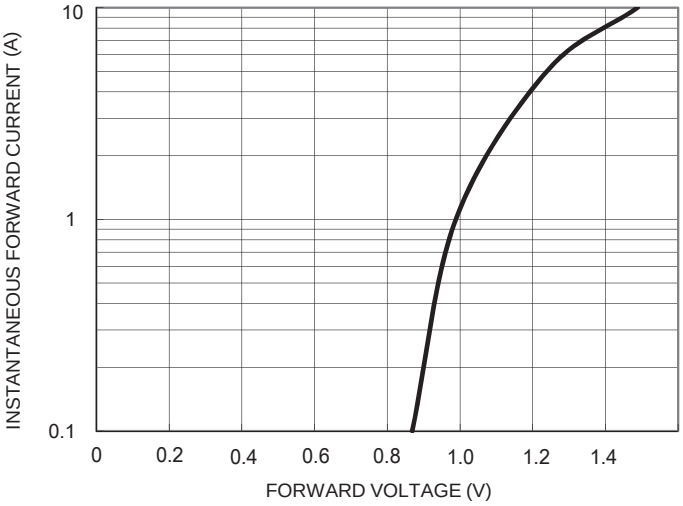


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

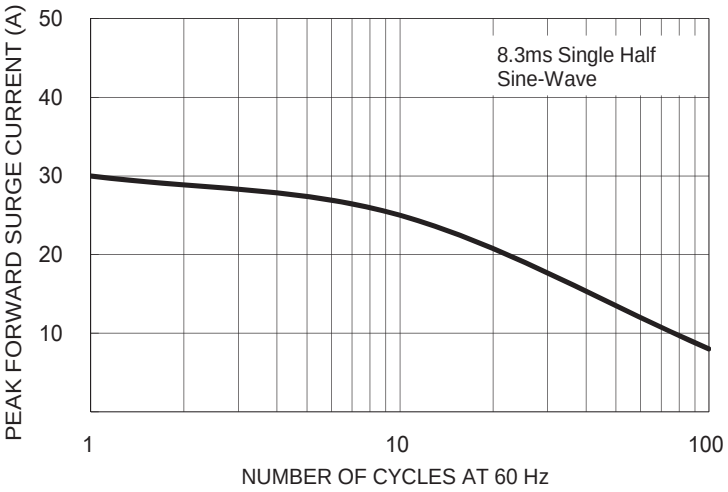


FIG. 4 TYPICAL REVERSE CHARACTERISTICS